

## E Series Power MOSFET

PRODUCT SUMMARY	
$V_{DS}$ (V) at $T_J$ max.	650
$R_{DS(on)}$ typ. ( $\Omega$ ) at 25 °C	$V_{GS} = 10$ V 0.082
$Q_g$ max. (nC)	132
$Q_{gs}$ (nC)	22
$Q_{gd}$ (nC)	46
Configuration	Single

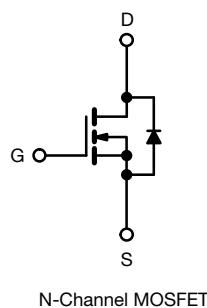
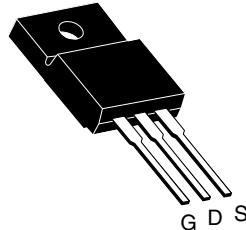
### FEATURES

- A specific on resistance ( $m\Omega \cdot cm^2$ ) reduction of 25 %
- Low figure-of-merit (FOM)  $R_{on} \times Q_g$
- Low input capacitance ( $C_{iss}$ )
- Reduced switching and conduction losses
- Ultra low gate charge ( $Q_g$ )
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
**HALOGEN**  
**FREE**

TO-220 FULLPAK



### APPLICATIONS

- Power factor correction power supplies (PFC)
- Hard switching PWM stages
- Computing
  - Switch mode power supplies (SMPS)
- Lighting
  - Light emitting diode (LED)
  - High intensity discharge (HID)
- Telecom
  - Server power supplies
- Renewable energy
  - Photovoltaic inverters
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Uninterruptable power supplies

### ORDERING INFORMATION

Package	TO-220 FULLPAK
Lead (Pb)-free and Halogen-free	SiHF35N60E-GE3

### ABSOLUTE MAXIMUM RATINGS ( $T_C = 25$ °C, unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	$V_{DS}$	600	V
Gate-Source Voltage	$V_{GS}$	$\pm 30$	
Continuous Drain Current ( $T_J = 150$ °C) <sup>e</sup>	$V_{GS}$ at 10 V	32	A
		20	
Pulsed Drain Current <sup>a</sup>	$I_{DM}$	80	
Linear Derating Factor		0.31	W/°C
Single Pulse Avalanche Energy <sup>b</sup>	$E_{AS}$	691	mJ
Maximum Power Dissipation	$P_D$	39	W
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 to +150	°C
Drain-Source Voltage Slope	$dV/dt$	57	V/ns
Reverse Diode $dV/dt$ <sup>d</sup>		31	
Soldering Recommendations (Peak temperature) <sup>c</sup>	For 10 s	300	°C
Mounting Torque	M3 screw	0.6	Nm

#### Notes

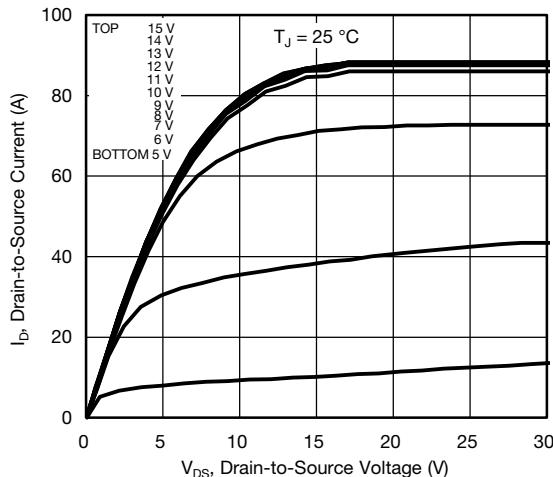
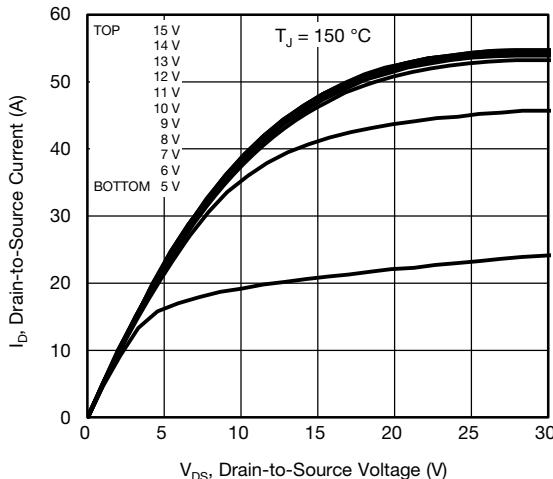
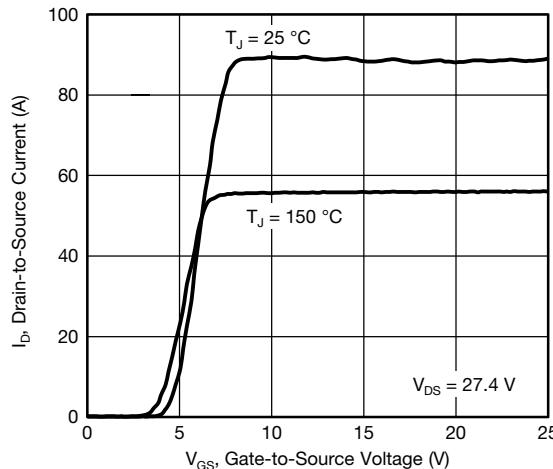
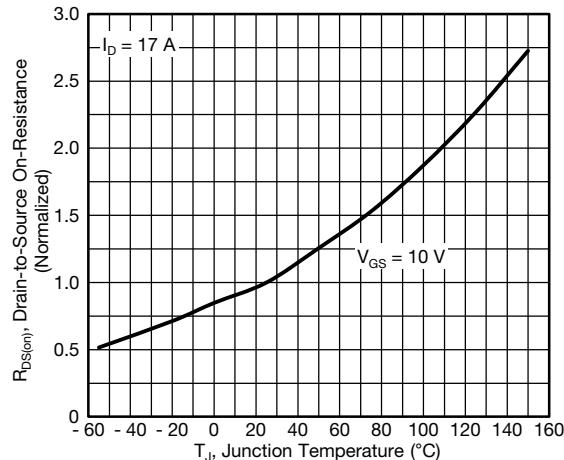
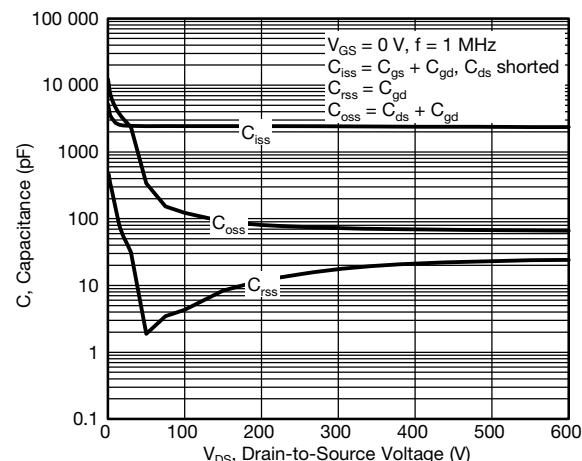
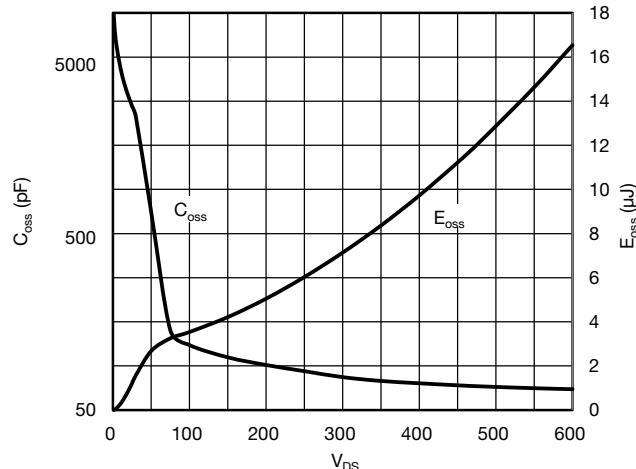
- Repetitive rating; pulse width limited by maximum junction temperature.
- $V_{DD} = 140$  V, starting  $T_J = 25$  °C,  $L = 28.2$  mH,  $R_g = 25$  Ω,  $I_{AS} = 7$  A.
- 1.6 mm from case.
- $I_{SD} \leq I_D$ ,  $dI/dt = 100$  A/μs, starting  $T_J = 25$  °C.
- Limited by maximum junction temperature.

<b>THERMAL RESISTANCE RATINGS</b>				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	$R_{thJA}$	-	65	
Maximum Junction-to-Case (Drain)	$R_{thJC}$	-	3.2	°C/W

<b>SPECIFICATIONS</b> ( $T_J = 25^\circ\text{C}$ , unless otherwise noted)								
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
<b>Static</b>								
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}$ , $I_D = 250 \mu\text{A}$		600	-	-	V	
$V_{DS}$ Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to $25^\circ\text{C}$ , $I_D = 1 \text{ mA}$		-	0.70	-	$^\circ\text{C}/\text{C}$	
Gate-Source Threshold Voltage (N)	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 250 \mu\text{A}$		2	-	4	V	
Gate-Source Leakage	$I_{GSS}$	$V_{GS} = \pm 20 \text{ V}$		-	-	$\pm 100$	nA	
		$V_{GS} = \pm 30 \text{ V}$		-	-	$\pm 1$	$\mu\text{A}$	
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 600 \text{ V}$ , $V_{GS} = 0 \text{ V}$		-	-	1		
		$V_{DS} = 480 \text{ V}$ , $V_{GS} = 0 \text{ V}$ , $T_J = 125^\circ\text{C}$		-	-	25	$\mu\text{A}$	
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 10 \text{ V}$	$I_D = 17 \text{ A}$	-	0.082	0.094	$\Omega$	
Forward Transconductance	$g_{fs}$	$V_{DS} = 30 \text{ V}$ , $I_D = 17 \text{ A}$		-	13	-	S	
<b>Dynamic</b>								
Input Capacitance	$C_{iss}$	$V_{GS} = 0 \text{ V}$ , $V_{DS} = 100 \text{ V}$ , $f = 1 \text{ MHz}$		-	2760	-	pF	
Output Capacitance	$C_{oss}$			-	118	-		
Reverse Transfer Capacitance	$C_{rss}$			-	5	-		
Effective Output Capacitance, Energy Related <sup>a</sup>	$C_{o(er)}$	$V_{DS} = 0 \text{ V}$ to $480 \text{ V}$ , $V_{GS} = 0 \text{ V}$		-	118	-		
Effective Output Capacitance, Time Related <sup>b</sup>	$C_{o(tr)}$			-	429	-		
Total Gate Charge	$Q_g$		$V_{GS} = 10 \text{ V}$	$I_D = 17 \text{ A}$ , $V_{DS} = 480 \text{ V}$	-	88	132	nC
Gate-Source Charge	$Q_{gs}$				-	22	-	
Gate-Drain Charge	$Q_{gd}$				-	46	-	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 480 \text{ V}$ , $I_D = 17 \text{ A}$ , $V_{GS} = 10 \text{ V}$ , $R_g = 9.1 \Omega$			-	29	58	ns
Rise Time	$t_r$				-	61	92	
Turn-Off Delay Time	$t_{d(off)}$				-	78	117	
Fall Time	$t_f$				-	32	64	
Gate Input Resistance	$R_g$	$f = 1 \text{ MHz}$ , open drain		0.25	0.5	1	$\Omega$	
<b>Drain-Source Body Diode Characteristics</b>								
Continuous Source-Drain Diode Current	$I_S$	MOSFET symbol showing the integral reverse p - n junction diode		-	-	32	A	
Pulsed Diode Forward Current	$I_{SM}$			-	-	80		
Diode Forward Voltage	$V_{SD}$	$T_J = 25^\circ\text{C}$ , $I_S = 17 \text{ A}$ , $V_{GS} = 0 \text{ V}$		-	0.9	1.2	V	
Reverse Recovery Time	$t_{rr}$	$T_J = 25^\circ\text{C}$ , $I_F = I_S = 17 \text{ A}$ , $dI/dt = 100 \text{ A}/\mu\text{s}$ , $V_R = 25 \text{ V}$		-	455	910	ns	
Reverse Recovery Charge	$Q_{rr}$			-	8	16	$\mu\text{C}$	
Reverse Recovery Current	$I_{RRM}$			-	30	-	A	

**Notes**

a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .  
b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .

**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

**Fig. 1 - Typical Output Characteristics**

**Fig. 2 - Typical Output Characteristics**

**Fig. 3 - Typical Transfer Characteristics**

**Fig. 4 - Normalized On-Resistance vs. Temperature**

**Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage**

**Fig. 6 - Coss and Eoss vs. VDS**

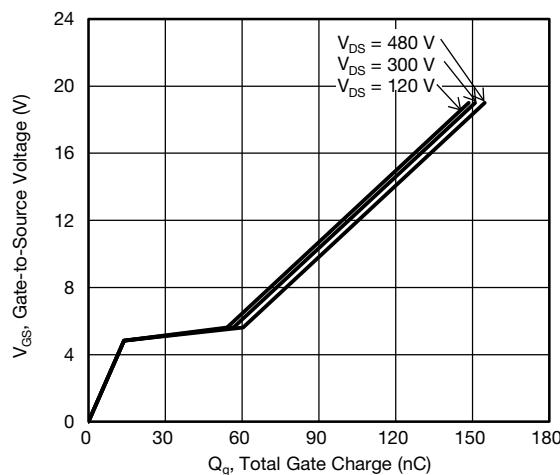


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

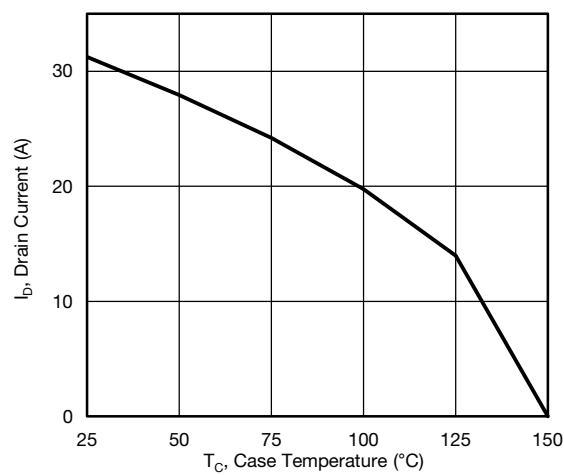


Fig. 10 - Maximum Drain Current vs. Case Temperature

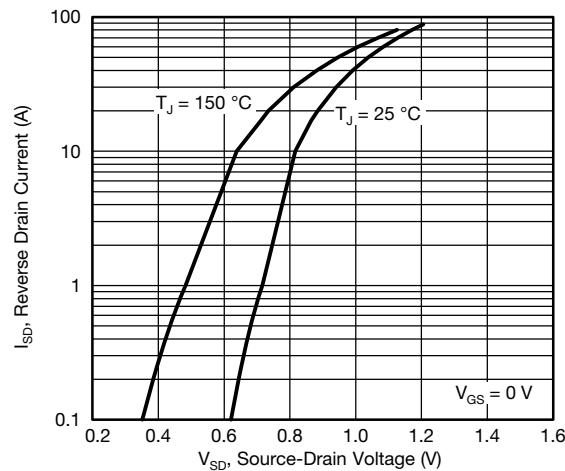


Fig. 8 - Typical Source-Drain Diode Forward Voltage

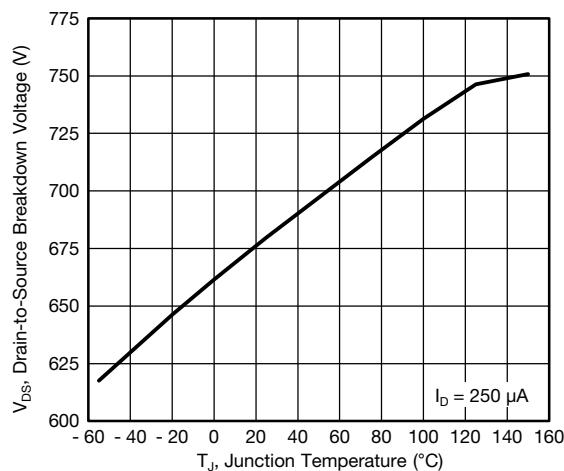


Fig. 11 - Temperature vs. Drain-to-Source Voltage

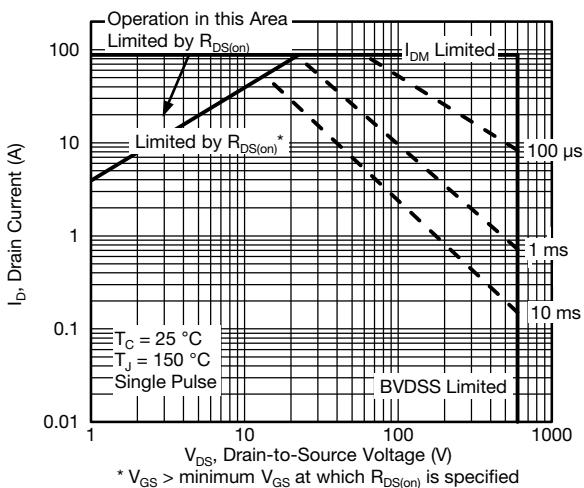
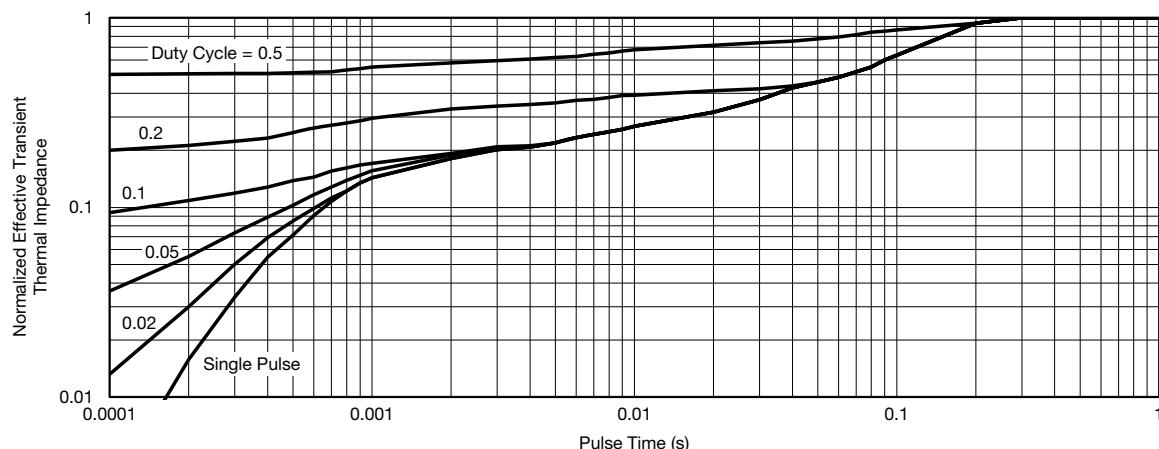
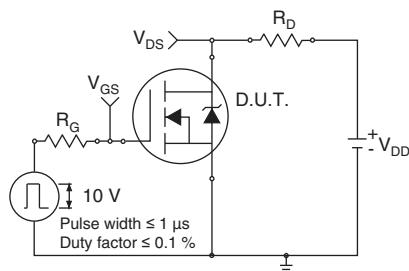


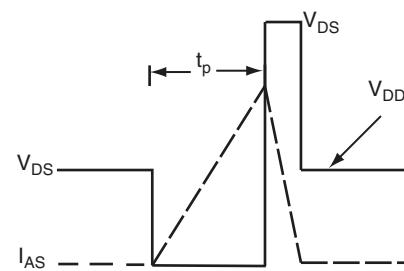
Fig. 9 - Maximum Safe Operating Area



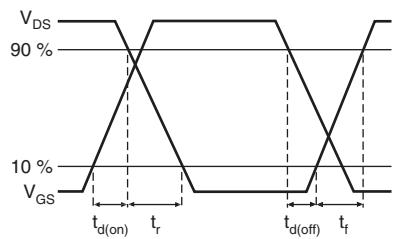
**Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case**



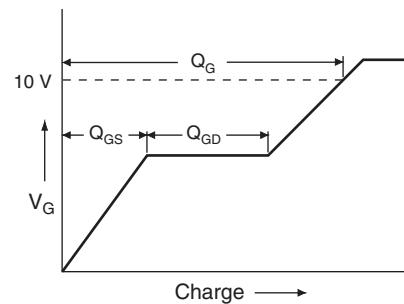
**Fig. 13 - Switching Time Test Circuit**



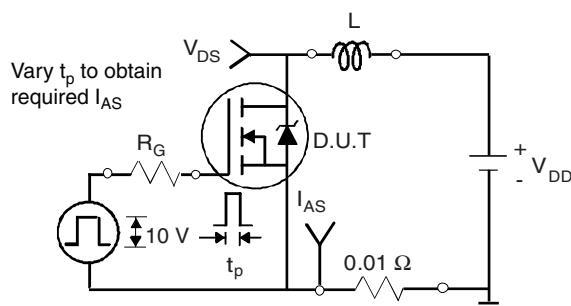
**Fig. 16 - Unclamped Inductive Waveforms**



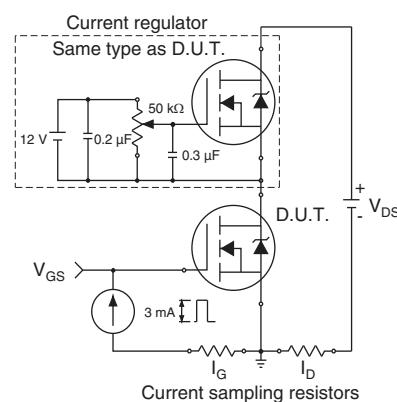
**Fig. 14 - Switching Time Waveforms**



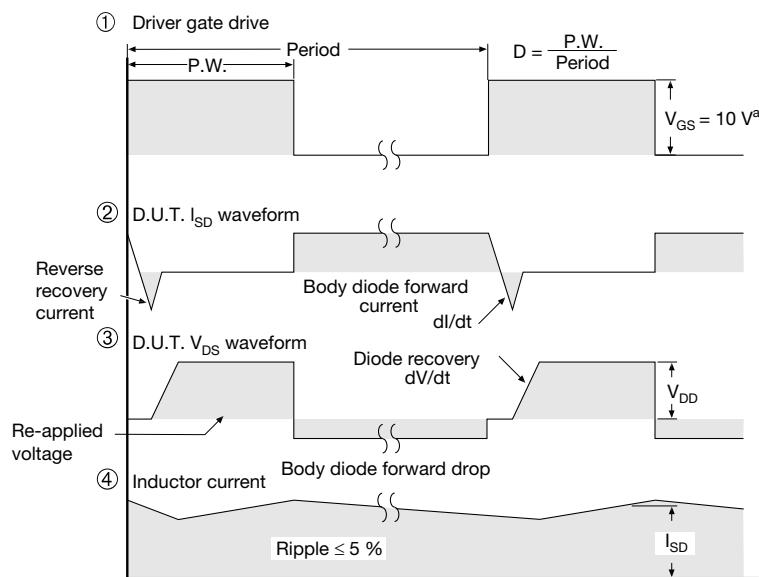
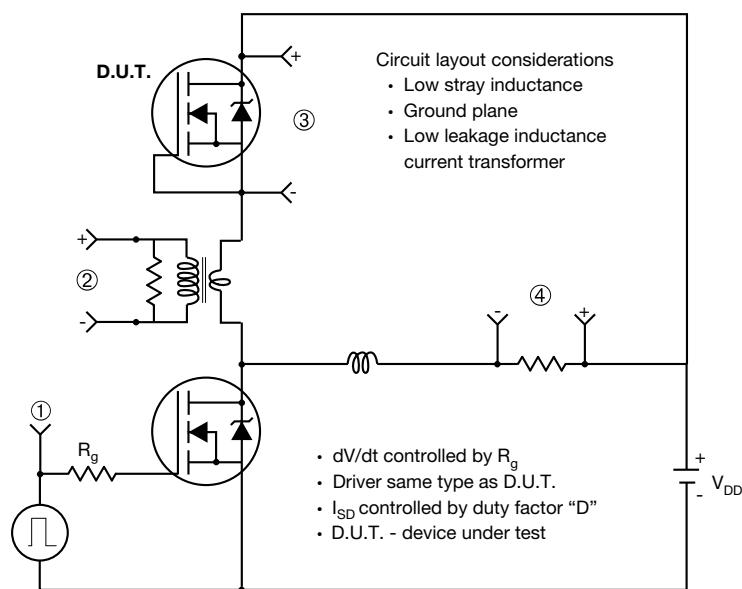
**Fig. 17 - Basic Gate Charge Waveform**



**Fig. 15 - Unclamped Inductive Test Circuit**



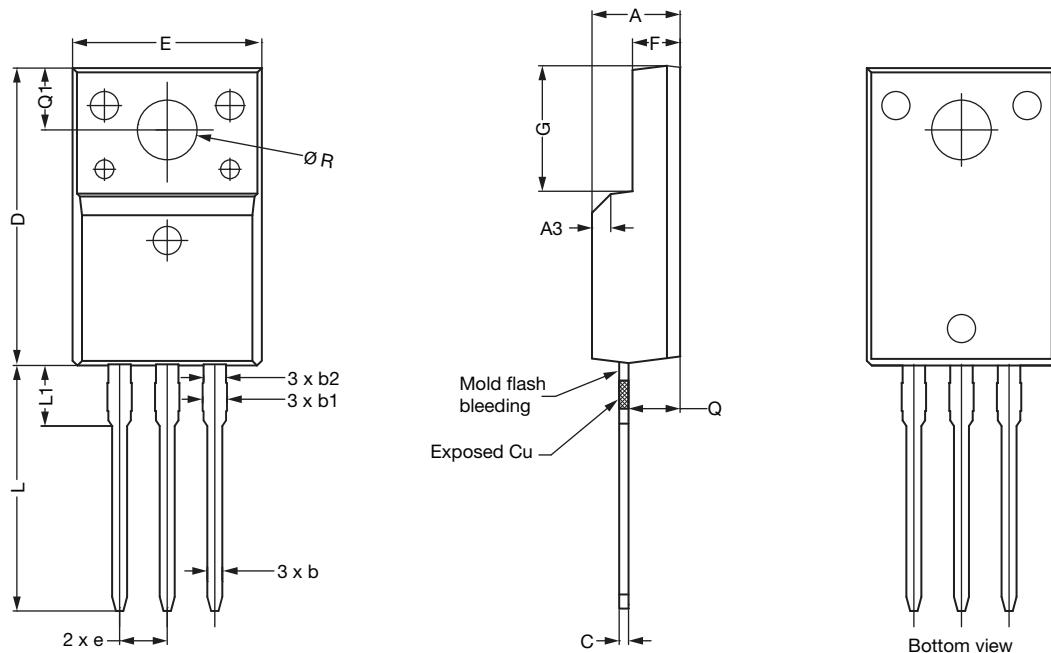
**Fig. 18 - Gate Charge Test Circuit**

**Peak Diode Recovery dV/dt Test Circuit**

**Fig. 19 - For N-Channel**

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## TO-220 FULLPAK (High Voltage)

### OPTION 1: FACILITY CODE = 9

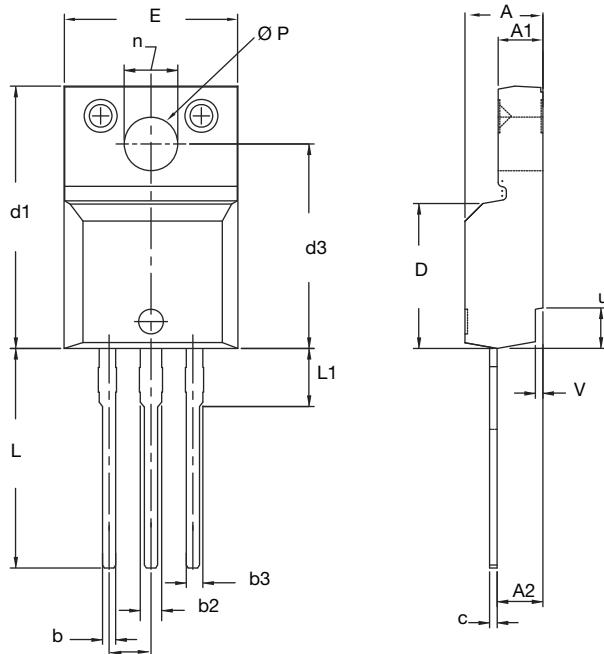


MILLIMETERS			
DIM.	MIN.	NOM.	MAX.
A	4.60	4.70	4.80
b	0.70	0.80	0.91
b1	1.20	1.30	1.47
b2	1.10	1.20	1.30
C	0.45	0.50	0.63
D	15.80	15.87	15.97
e	2.54 BSC		
E	10.00	10.10	10.30
F	2.44	2.54	2.64
G	6.50	6.70	6.90
L	12.90	13.10	13.30
L1	3.13	3.23	3.33
Q	2.65	2.75	2.85
Q1	3.20	3.30	3.40
Ø R	3.08	3.18	3.28

#### Notes

1. To be used only for process drawing
2. These dimensions apply to all TO-220 FULLPAK leadframe versions 3 leads
3. All critical dimensions should C meet  $C_{pk} > 1.33$
4. All dimensions include burrs and plating thickness
5. No chipping or package damage
6. Facility code will be the 1<sup>st</sup> character located at the 2<sup>nd</sup> row of the unit marking

### OPTION 2: FACILITY CODE = Y



	MILLIMETERS		INCHES	
DIM.	MIN.	MAX.	MIN.	MAX.
A	4.570	4.830	0.180	0.190
A1	2.570	2.830	0.101	0.111
A2	2.510	2.850	0.099	0.112
b	0.622	0.890	0.024	0.035
b2	1.229	1.400	0.048	0.055
b3	1.229	1.400	0.048	0.055
c	0.440	0.629	0.017	0.025
D	8.650	9.800	0.341	0.386
d1	15.88	16.120	0.622	0.635
d3	12.300	12.920	0.484	0.509
E	10.360	10.630	0.408	0.419
e	2.54 BSC		0.100 BSC	
L	13.200	13.730	0.520	0.541
L1	3.100	3.500	0.122	0.138
n	6.050	6.150	0.238	0.242
$\varnothing P$	3.050	3.450	0.120	0.136
u	2.400	2.500	0.094	0.098
V	0.400	0.500	0.016	0.020

ECN: E19-0180-Rev. D, 08-Apr-2019  
 DWG: 5972

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2. These dimensions apply to all TO-220 FULLPAK leadframe versions 3 leads
3. All critical dimensions should C meet  $C_{pk} > 1.33$
4. All dimensions include burrs and plating thickness
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